

CLAIMS

1. An insulating resin composition to be used to form insulating layer(s) of a multilayer printed-wiring board, comprising two or more kinds of resins which are different in etching rate by plasma treatment and which are not compatible with each other, so that the surface of the resulting insulating layer can be made uneven by the plasma treatment.

2. A multilayer printed-wiring board having insulating layer(s) resulting from the insulating resin composition as set forth in claim 1, which layer(s) have a surface roughness (i.e., unevenness) degree by the plasma treatment of 100 - 4,000 nm.

NOTEED "4906560

Gold
R2